

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **HORNG-WEN CHEN AND CHI-HOW WU**

For: **AN IN-SITU STRIP PROCESS FOR POLYSILICON ETCHING IN DEEP SUB-MICRON TECHNOLOGY**

Enclosed are:

- ☒ **6** sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Taiwan Semiconductor Manufacturing Company**
- ☐ An associate power of attorney

The filing fee has been calculated as shown below:

|                                    | (Col. 1)  | (Col. 2)  | OTHER THAN A SMALL ENTITY |         |
|------------------------------------|-----------|-----------|---------------------------|---------|
| FOR:                               | NO. FILED | NO. EXTRA | RATE                      | FEE     |
| BASIC FEE                          |           |           |                           | \$ 690. |
| TOTAL CLAIMS                       | 20 -20=   | 0         | x 18 =                    | \$ 0.   |
| INDEP CLAIMS                       | 3 -3=     | 0         | x 78 =                    | \$ 0.   |
| MULTIPLE DEPENDENT CLAIM PRESENTED |           |           | + 260 =                   |         |
|                                    |           |           | SUB TOTAL                 | \$ 690. |
|                                    |           |           | ASSIGNMENT                | \$40.   |
|                                    |           |           | TOTAL                     | \$ 730. |

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 730. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

  
STEPHEN B. ACKERMAN, REG. NO. 37,761